

<b>Form 1449 (Modified)</b>  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	NSC1P223/P05081	10/006,482
	Applicant:	
	BRANCHEVSKY	
	Filing Date	Group
	12/06/01	3729

### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
TTN	1	4,082,906	04/04/78	Amin et al.	428	539	02/14/77
	2	4,471,406	09/11/84	Sawairi	361	328	09/29/82
	3	4,517,406	05/14/85	Erdle	174	72	05/14/84
	4	4,734,818	03/29/88	Hernandez et al.	361	306	03/19/87
	5	4,740,863	04/26/88	Langlois	361	309	05/15/87
	6	4,748,537	05/31/88	Hernandez et al.	361	306	08/08/87
	7	5,027,253	06/25/91	Lauffer et al.	361	321	04/09/90
	8	5,036,424	07/30/91	Yokotani et al.	361	321	05/18/90
	9	5,046,236	09/10/91	Wada et al.	29	610.1	10/10/90
TTN	10	5,319,517	06/07/94	Nomura et al.	361	321.4	03/29/93

### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
TTN	17	Delaney, <i>Characterization and Performance Prediction for Integral Capacitors in Low Temperature Co-Fired Ceramic Technology</i> , IEEE Transactions on Advanced Packaging, Vol. 22, No. 1, February 1999, pg. 68-77
TTN	18	Delaney, <i>Characterisation of the Electrical Performance of Buried Capacitors and Resistors in Low Temperature Co-Fired (LTCC) Ceramic</i> , IEEE Electronic Components and Technology Conference, 1998, pg. 900-908
TTN	19	Scrantom, <i>Manufacture of Embedded Integrated Passive Components into Low Temperature Co-Fired Ceramic Systems</i> , International Symposium on Microelectronics, 1998, pg. 459-466
Examiner <i>Tuyen Nguyen</i>		Date Considered <i>10/31/03</i>

Examiner: Initial citation considered. Draw line through citation if not in conformity and not considered. Include copy of this form with next communication to applicant.



<b>Form 1449 (Modified)</b> <b>Information Disclosure Statement By Applicant</b> (Use Several Sheets if Necessary)	Atty Docket No. <b>NSC1P223/P05081</b> Applicant: <b>BRANCHEVSKY</b> Filing Date <b>12/06/01</b>	Application No.: <b>10/006,482</b> Group <b>3729</b>
--	---	---

RECEIVED  
MAR 26 2002  
TECHNOLOGY CENTER 2800

#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
TTN	11	5,661,882	09/02/97	Alexander	29	25.42	06/30/95
	12	5,687,055	11/11/97	Miki	361	305	01/04/95
	13	5,736,448	04/07/98	Saia et al.	438	393	12/04/95
	14	6,011,683	01/04/00	Dat	361	306.1	01/30/98
	15	6,061,228	05/09/00	Palmer et al.	361	306.2	04/28/98
TTN	16	6,252,761	06/26/01	Branchevsky	361	321.2	09/15/99

#### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
TTN	20	Müller, <i>3D-Integration of Passive RF-Components in LTCC</i> , Technical University of Ilmenau, Germany, pg. 211-216
TTN	21	Wersing, <i>Integrated Passive Components Using Low Temperature Cofired Ceramics</i> , International Symposium on Microelectronics, 1998, pg. 193-199
TTN	22	Drüe, <i>RF Models of Passive LTCC Components in the Lower Gigahertz-Range</i> , Applied Microwave & Wireless, Technical University of Ilmenau, Germany, April 1998, pg. 26-35
TTN	23	U.S. Patent Application No. 09/632,361, entitled "Embedded Green Multi-Layer Ceramic Chip Capacitor in a Low Temperature Co-Fired Ceramic (LTCC) Substrate, filed August 3, 2000
Examiner <i>Jaylen Nguyen</i>		Date Considered <i>10/31/01</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

RECEIVED  
APR 30 2002  
TECHNOLOGY CENTER 2800